



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE4274 V50		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001178492						
<b>Package</b>		PG-TO220-3-1		<b>Weight*</b>		2070.05 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.945	0.14	0.14	1423	1423
leadframe	non noble metal	iron	7439-89-6	0.816	0.04		394	
	inorganic material	phosphorus	7723-14-0	0.245	0.01		118	
	non noble metal	copper	7440-50-8	815.335	39.38	39.43	393872	394384
wire	non noble metal	aluminium	7429-90-5	0.175	0.01	0.01	85	85
encapsulation	organic material	carbon black	1333-86-4	1.268	0.06		613	
	plastics	epoxy resin	-	58.329	2.82		28178	
	inorganic material	silicondioxide	60676-86-0	574.414	27.75	30.63	277488	306279
leadfinish	non noble metal	tin	7440-31-5	21.462	1.04	1.04	10368	10368
plating	non noble metal	nickel	7440-02-0	0.244	0.01		118	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	393871	118
solder	noble metal	silver	7440-22-4	0.115	0.01		55	
	non noble metal	tin	7440-31-5	0.092	0.00		44	
	non noble metal	lead	7439-92-1	4.377	0.21	0.22	2114	2213
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		285	
	inorganic material	phosphorus	7723-14-0	0.177	0.01		86	
	non noble metal	copper	7440-50-8	589.466	28.48	28.52	284759	285130
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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